



# SOT162-1

plastic small outline package; 16 leads; body width 7.5 mm

8 February 2016

Package information

## 1. Package summary

|                                |                     |
|--------------------------------|---------------------|
| Terminal position code         | D (double)          |
| Package type descriptive code  | SO16                |
| Package type industry code     | SO16                |
| Package style descriptive code | SO (small outline)  |
| Package style suffix code      | NA (not applicable) |
| Package body material type     | P (plastic)         |
| IEC package outline code       | 075E03              |
| JEDEC package outline code     | MS-013              |
| Mounting method type           | S (surface mount)   |
| Issue date                     | 19-2-2003           |

Table 1. Package summary

| Symbol         | Parameter                      |  | Min   | Typ | Nom  | Max  | Unit |
|----------------|--------------------------------|--|-------|-----|------|------|------|
| D              | package length                 |  | 10.1  | -   | 10.2 | 10.5 | mm   |
| E              | package width                  |  | 7.4   | -   | 7.5  | 7.6  | mm   |
| A              | seated height                  |  | [tbd] | -   | 2.65 | 2.65 | mm   |
| A <sub>2</sub> | package height                 |  | 2.25  | -   | 2.35 | 2.45 | mm   |
| n <sub>2</sub> | actual quantity of termination |  | -     | -   | 16   | -    |      |



2. Package outline

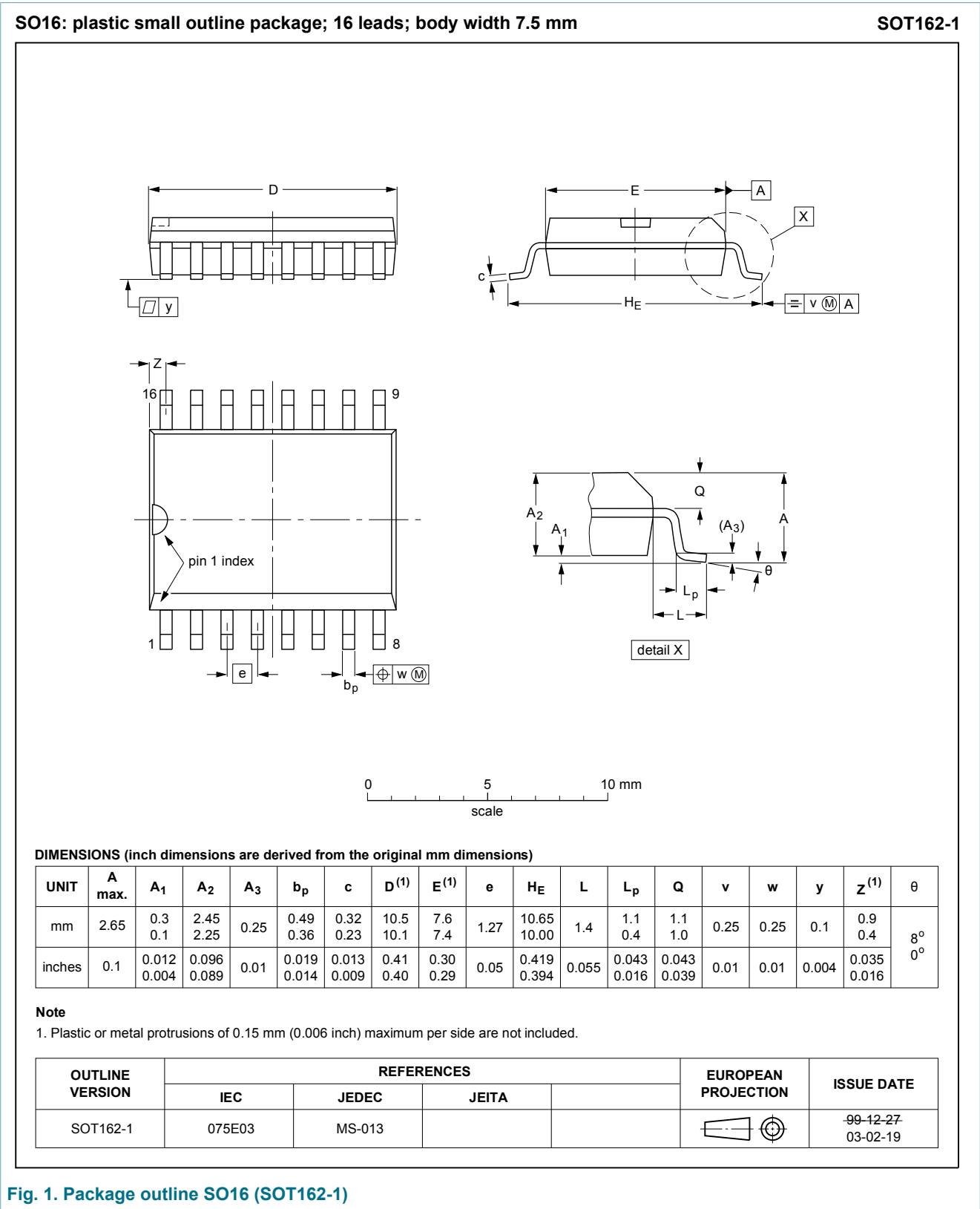
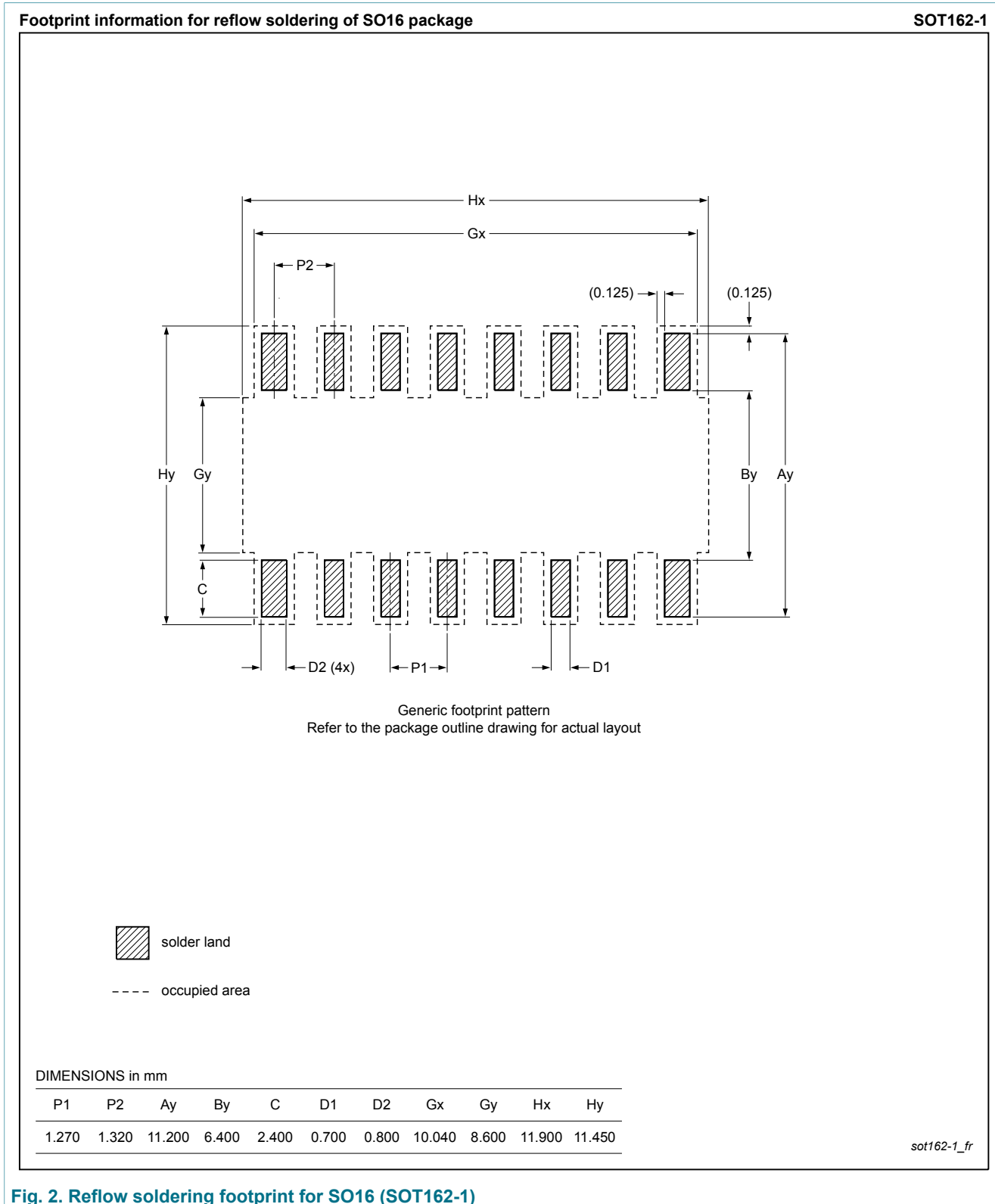


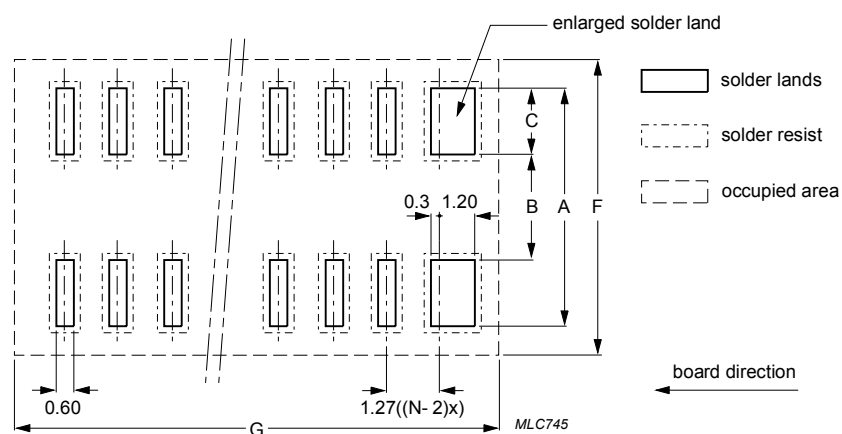
Fig. 1. Package outline SO16 (SOT162-1)

### 3. Soldering



**Fig. 2. Reflow soldering footprint for SO16 (SOT162-1)**

**plastic small outline package; 16 leads; body width 7.5 mm**



**Fig. 3. Wave soldering footprint for SO16 (SOT162-1)**

## 4. Legal information

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